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Förpackning av elektronikkomponenter för automatisk hantering – Del 3: Bandning av uttagslösa komponenter – Blisterband

*Packaging of components for automatic handling –
Part 3: Packaging of surface mount components on continuous tapes*

Som svensk standard gäller europastandarden EN 60286-3:2013. Den svenska standarden innehåller den officiella engelska språkversionen av EN 60286-3:2013.

Nationellt förord

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- **IEC 60286-3, Fifth edition, 2013 - Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes**

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English version

**Packaging of components for automatic handling -
Part 3: Packaging of surface mount components on continuous tapes
(IEC 60286-3:2013)**

Emballage de composants pour
opérations automatisées -
Partie 3: Emballage des composants pour
montage en surface en bandes continues
(CEI 60286-3:2013)

Gurtung und Magazinierung von
Bauelementen für die automatische
Verarbeitung -
Teil 3: Gurtung von
oberflächenmontierbaren Bauelementen
auf Endlogurten
(IEC 60286-3:2013)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 40/2200/FDIS, future edition 5 of IEC 60286-3, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60286-3:2013.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2014-03-21
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2016-06-21

This document supersedes EN 60286-3:2007.

EN 60286-3:2013 includes the following significant technical changes with respect to EN 60286-3:2007:

- a) integration of EN 60286-3-1:2009 as type 1b (Packaging of surface mount components on continuous pressed carrier tapes);
- b) integration of EN 60286-3-2:2009 as type 2b (Packaging of surface mount components on blister carrier tapes 4 mm in width).

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Endorsement notice

The text of the International Standard IEC 60286-3:2013 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60286-3-1:2009	NOTE	Harmonised as EN 60286-3-1:2009 (not modified).
IEC 60286-3-2:2009	NOTE	Harmonised as EN 60286-3-2:2009 (not modified).
IEC/TR 62258-3	NOTE	Harmonised as CLC/TR 62258-3.
ISO 11469	NOTE	Harmonised as EN ISO 11469.

Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-2	-	Mechanical standardization of semiconductor devices - Part 2: Dimensions	-	-
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC/TR 61340-5-2	-	Electrostatics - Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide	CLC/TR 61340-5-2	-

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INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components and singulated dies for test purposes and other operations.

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 3: Packaging of surface mount components on continuous tapes

1 General

1.1 Scope

This part of IEC 60286 is applicable to the tape packaging of electronic components without leads or with lead stumps, intended to be connected to electronic circuits. It includes only those dimensions that are essential for the taping of components intended for the above-mentioned purposes.

This standard also includes requirements related to the packaging of singulated die products including bare die and bumped die (flip chips).

1.2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-2, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC/TR 61340-5-2, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*